

ECE 2300
Digital Logic & Computer Organization
Spring 2025

Memories

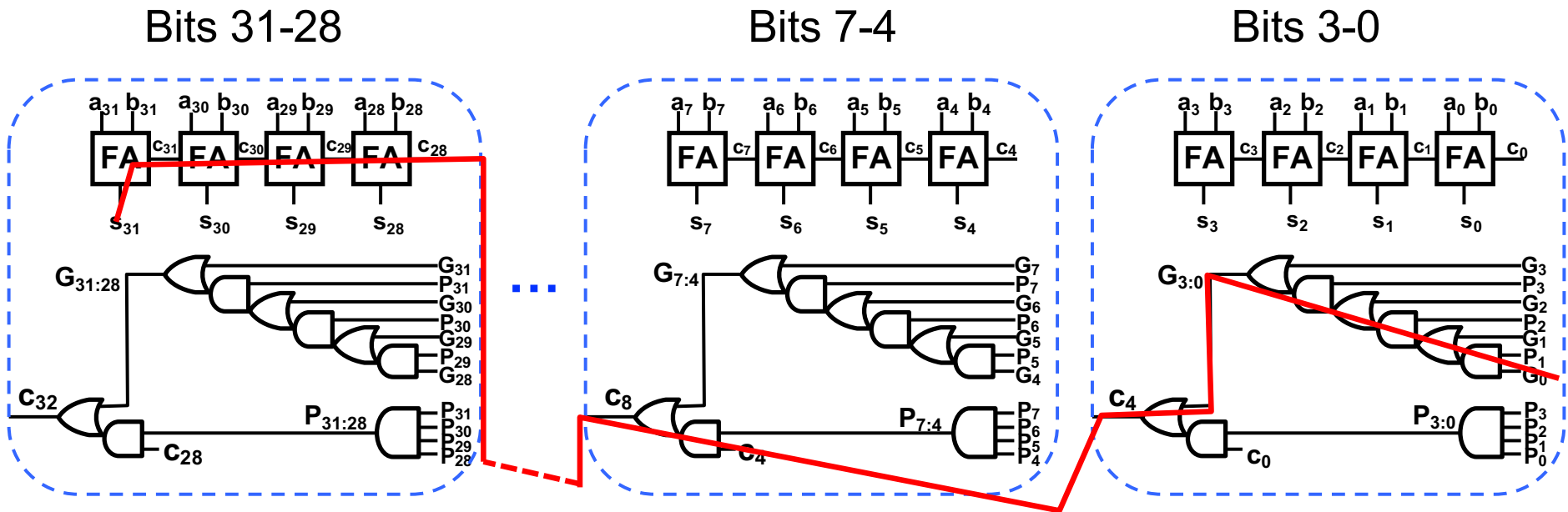


Cornell University

Announcements

- **Final exam is scheduled on Saturday May 10 @ 9am**
- **Lab 3a due tomorrow**

Review: Critical Path of 32-bit CLA

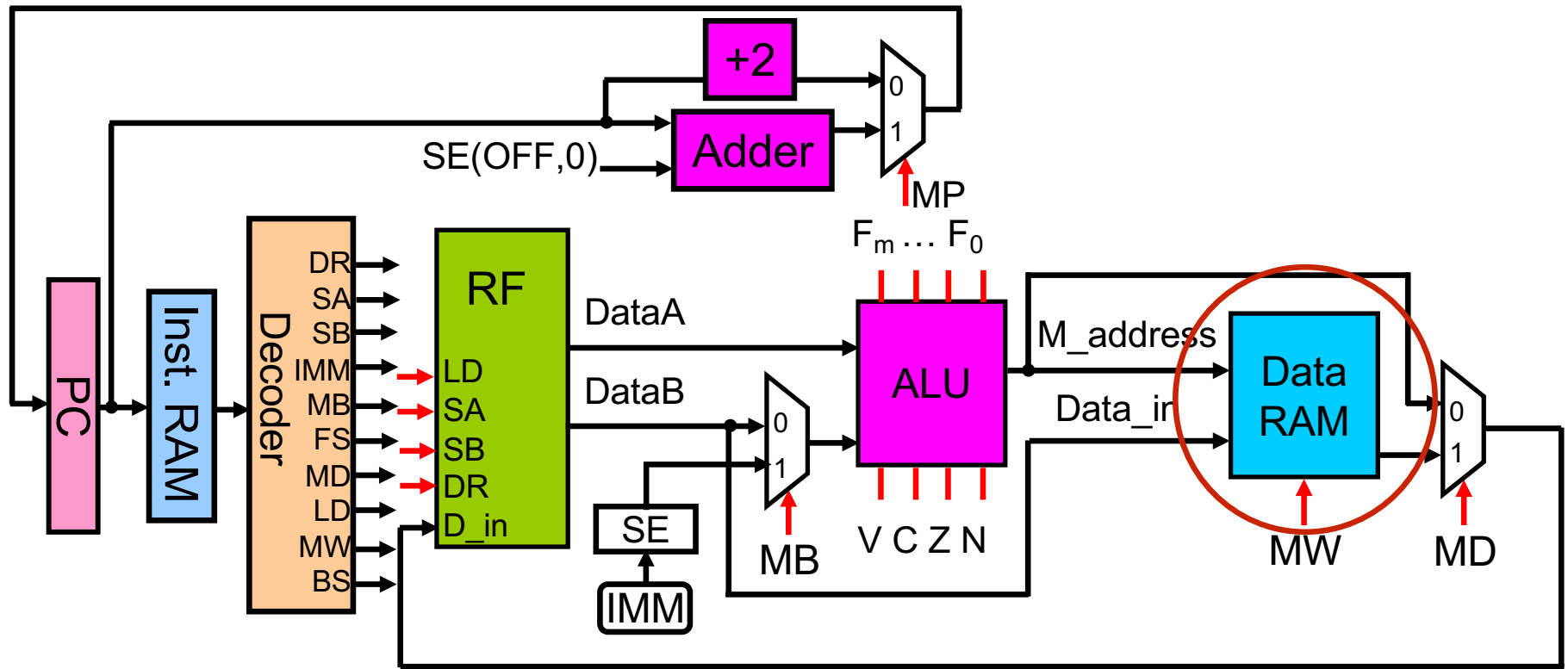


Carry generation and propagation functions (e.g., $G_{7:4}$, $P_{7:4}$) in a 4-bit CLA block do not depend on results from other CLA blocks



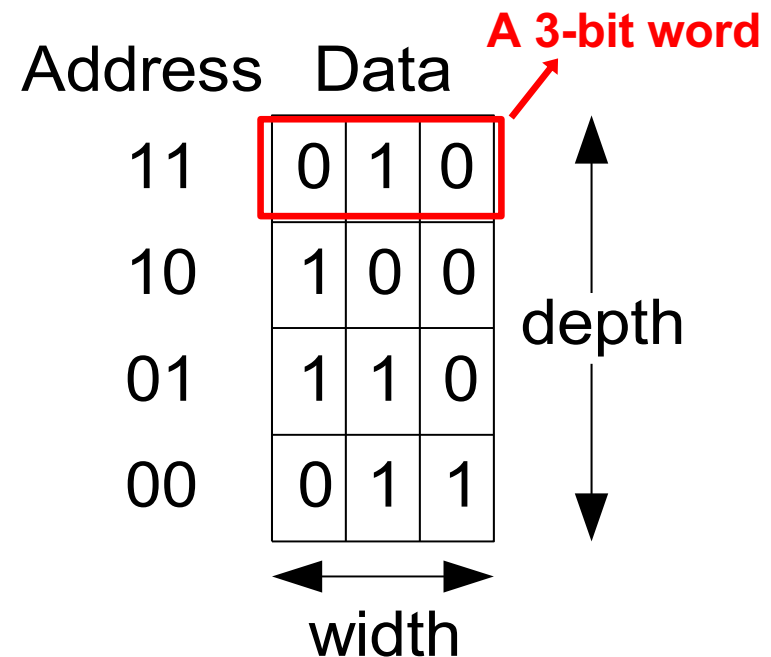
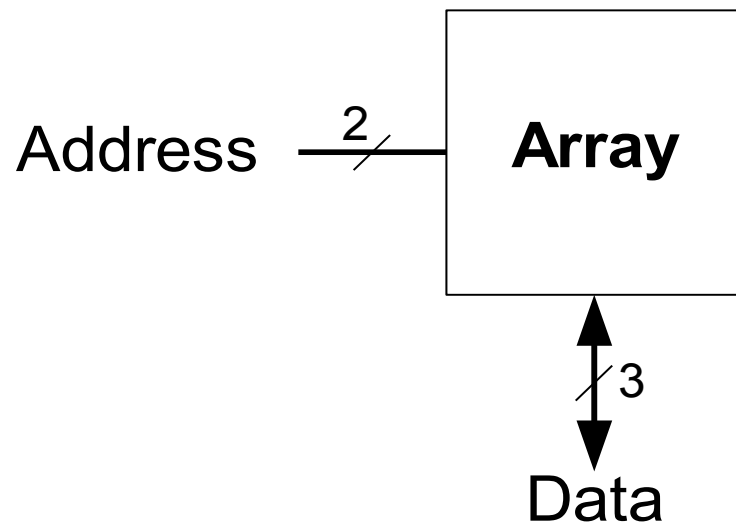
P 's and G 's for all CLA blocks are generated *in parallel*

Our Microprocessor Needs (Large) Memory

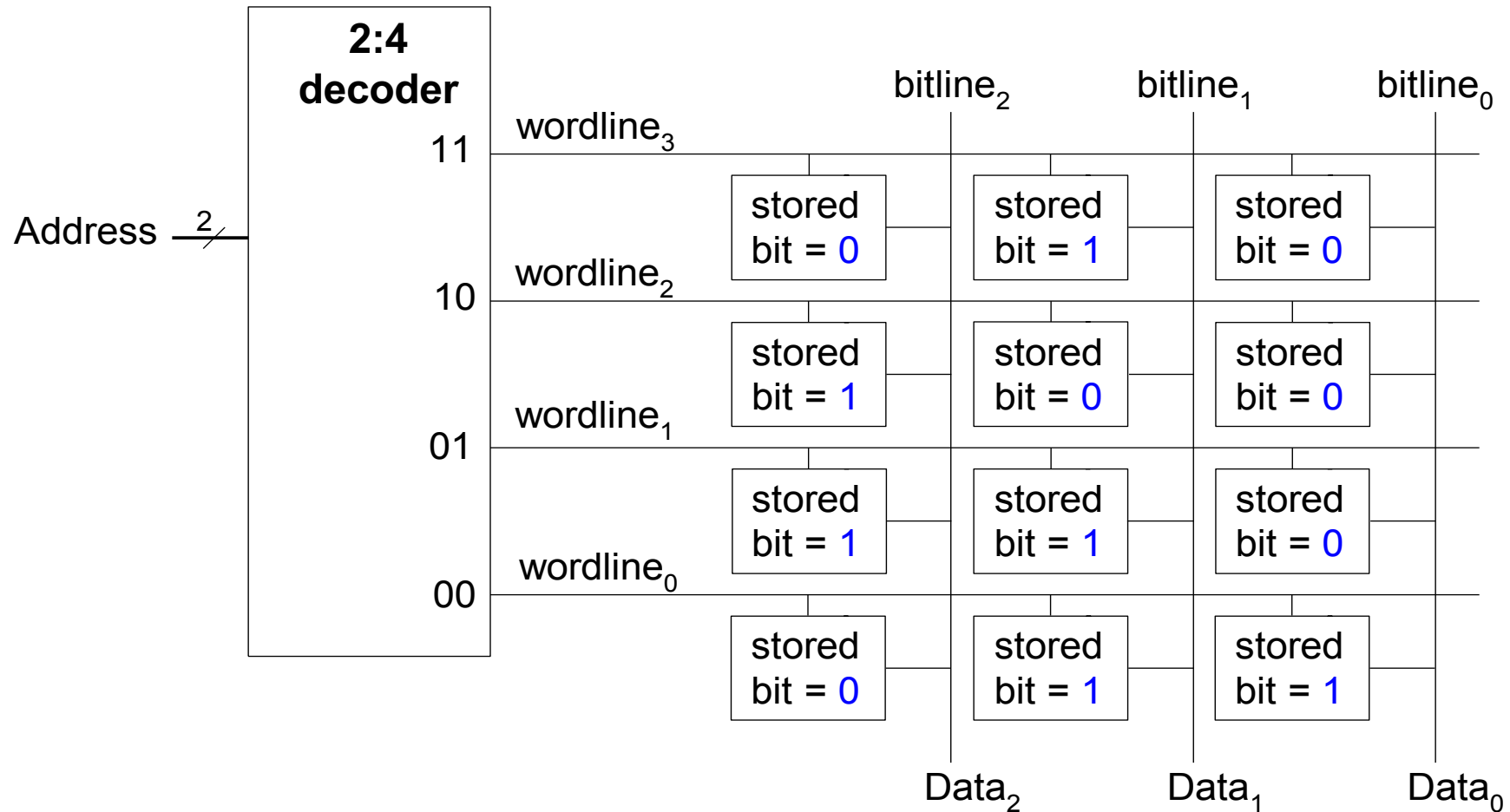


Memory Organization: An Abstract View

- **Two dimensional array of bit cells**
 - Each bit cell stores 1 bit
- **Address selects a word with multiple bits**



General Memory Structure

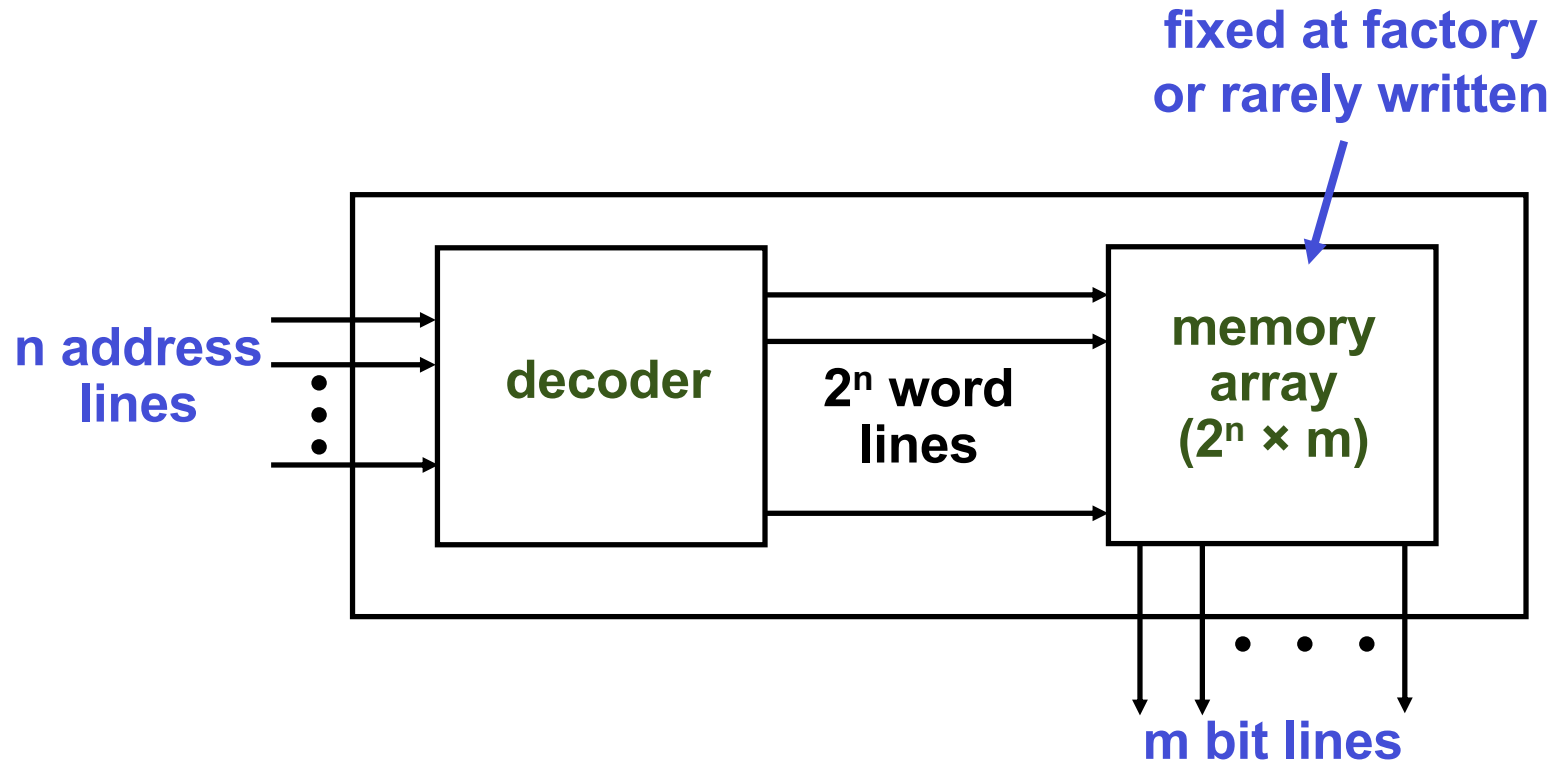


Only one wordline is asserted at any given time

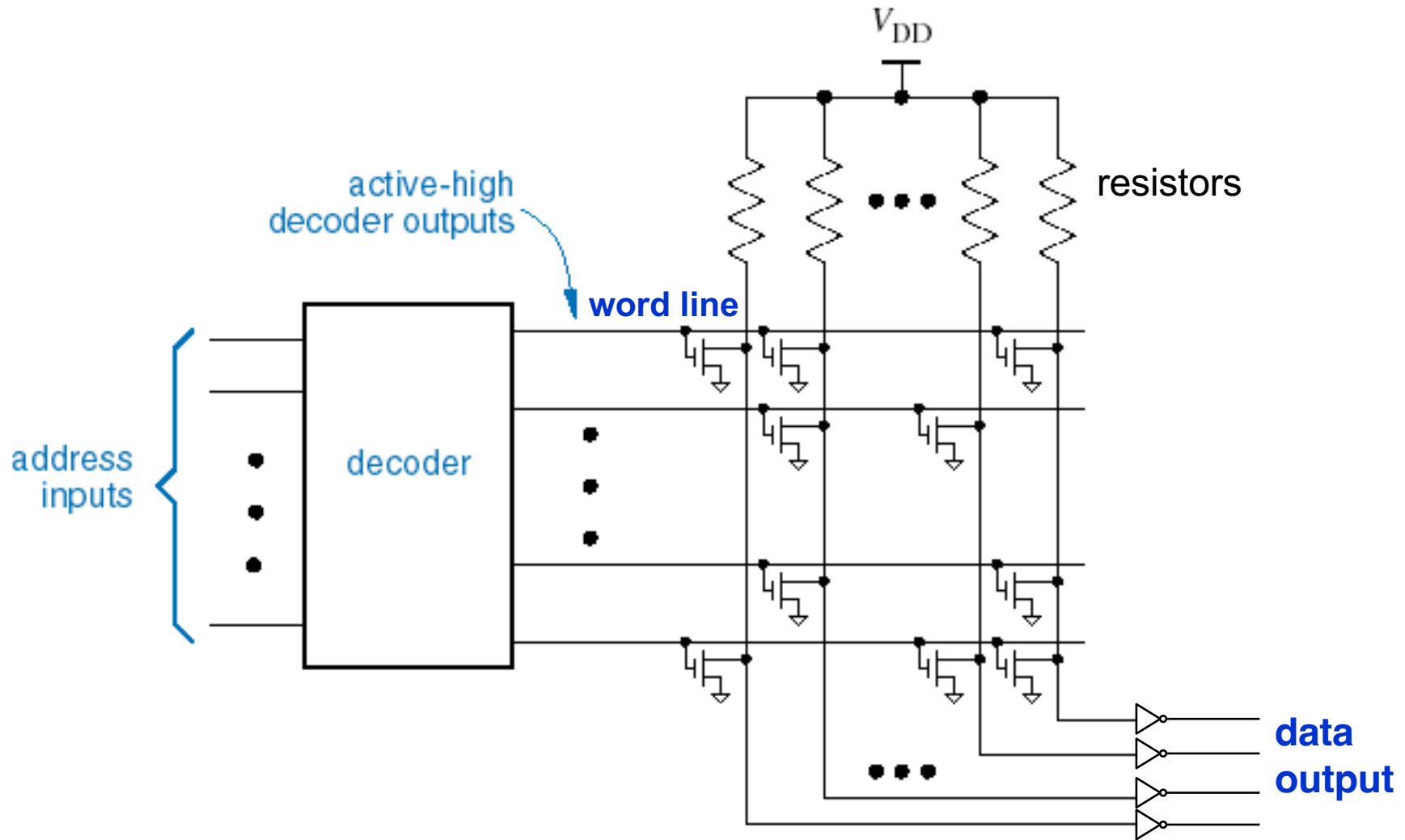
Types of Memories

- **Read-Only Memory (ROM)**
 - Truly read-only
 - Written in the factory, and never written after installation
 - Mostly read and rarely written
 - Much faster to read than write
 - Usually non-volatile
- **Random Access Memory (RAM)**
 - Dynamic RAM (DRAM), Static RAM (SRAM)
 - Read and write any location at similar speeds
 - Typically volatile: loses contents when powered off
 - New classes of non-volatile/persistent RAMs are emerging

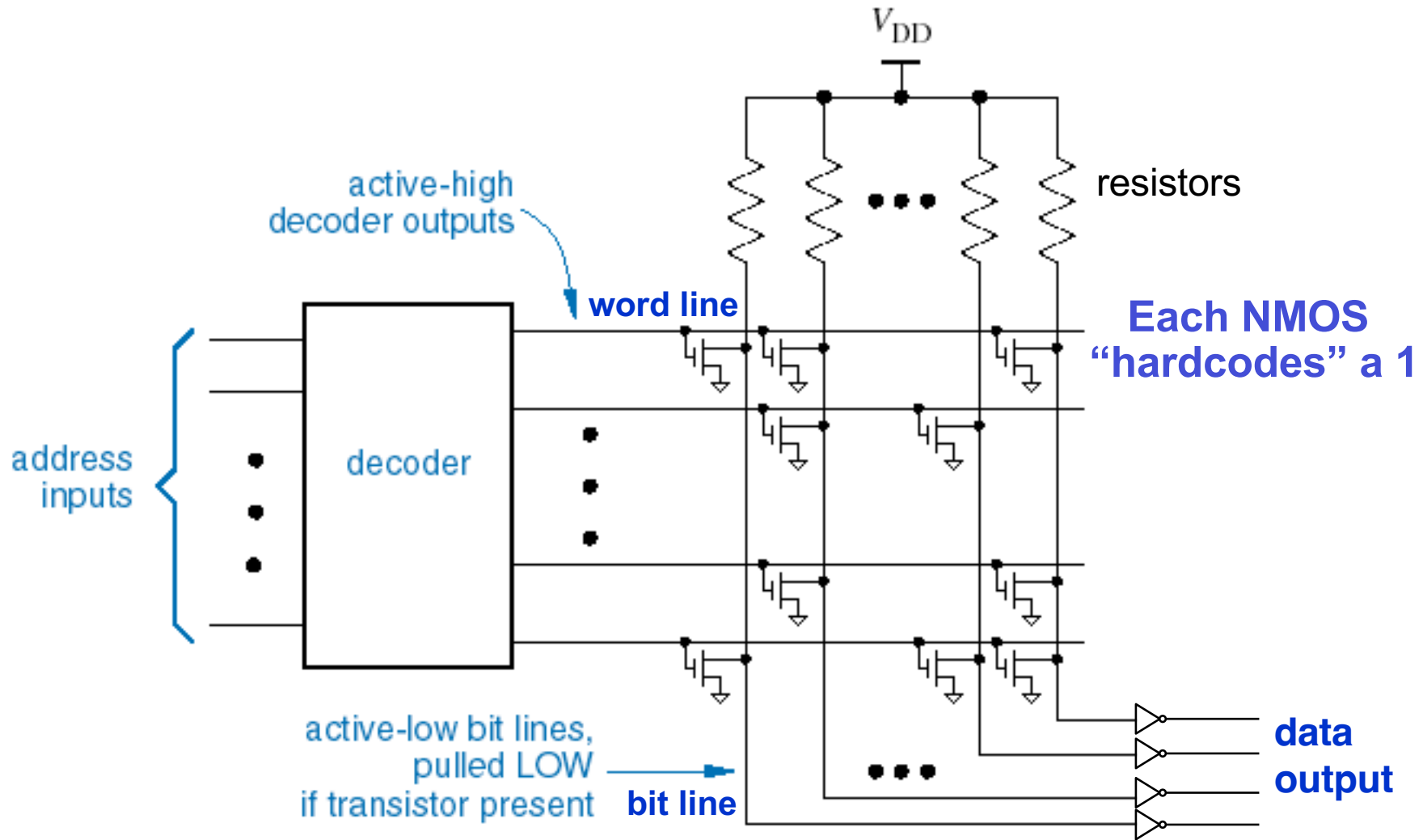
Read-Only Memory (ROM) Structure



Example ROM Implementation



Example ROM Implementation



Applications of ROM

- **Data & program storage**
 - e.g., **Boot configuration for personal computers or application code for embedded systems**
- **Combinational logic functions**
 - **Lookup table**
 - **Address inputs = function inputs**
 - **Data outputs = function outputs**

Using ROMs for Combinational Logic

$$F_0 = A' B' C + A B' C' + A B' C$$

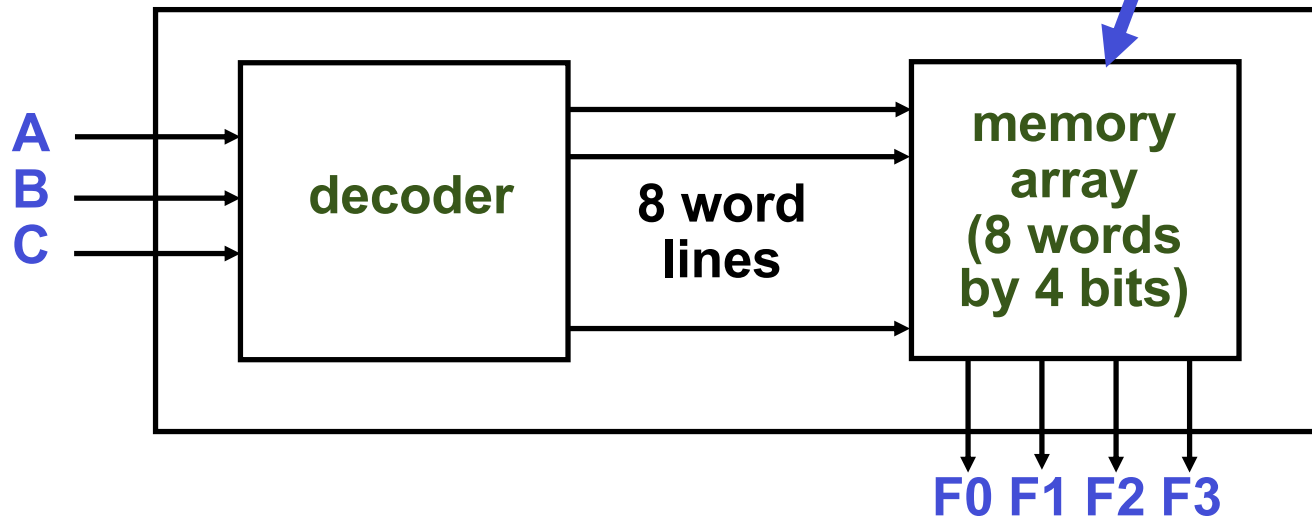
$$F_1 = A' B' C + A' B C' + A B C$$

$$F_2 = A' B' C' + A' B' C + A B' C'$$

$$F_3 = A' B C + A B' C' + A B C'$$



A	B	C	F0	F1	F2	F3
0	0	0	0	0	1	0
0	0	1	1	1	1	0
0	1	0	0	1	0	0
0	1	1	0	0	0	1
1	0	0	1	0	1	1
1	0	1	1	0	0	0
1	1	0	0	0	0	1
1	1	1	0	1	0	0



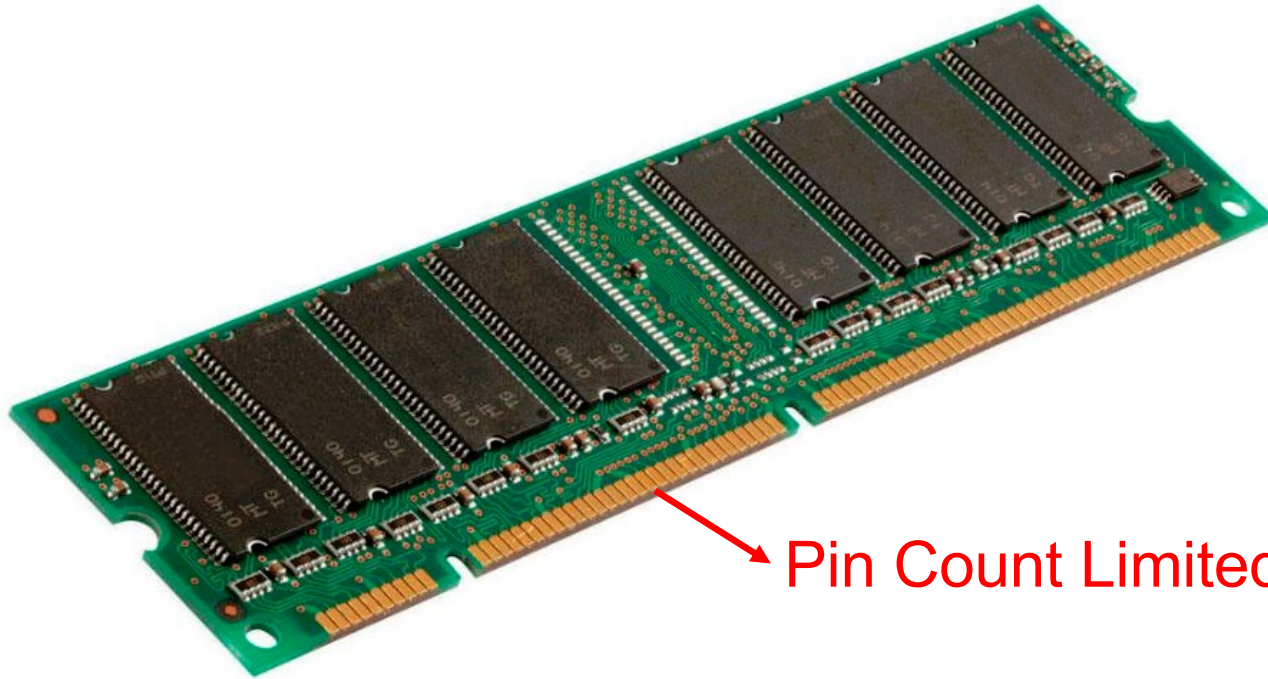
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- **Random Access Memory (RAM)**
 - **Dynamic RAM (DRAM), Static RAM (SRAM)**
 - Read and write any location at similar speeds
 - Typically volatile: loses contents when powered off
 - Note: new emerging classes of non-volatile/persistent RAMs are emerging

Dynamic RAMs (DRAMs)

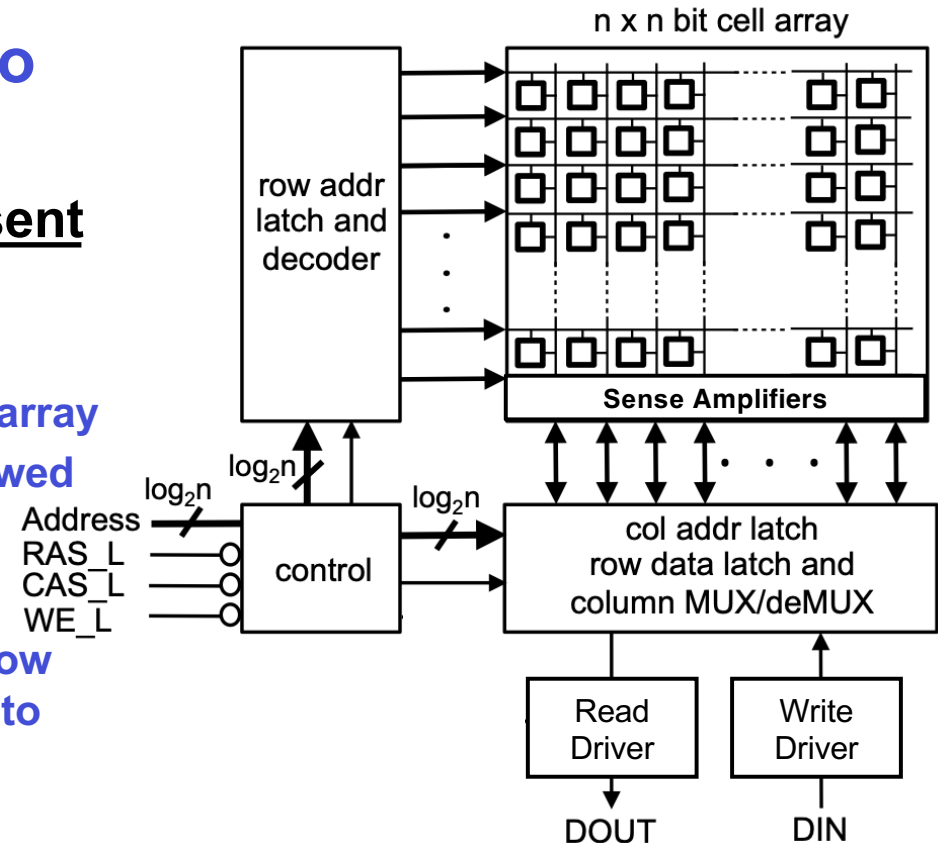
- DRAM modules are usually off-chip and mounted on a separate printed circuit board



- In a typical DRAM, the smallest unit is the memory cell, which forms arrays
 - Arrays make up banks; banks are organized into ranks

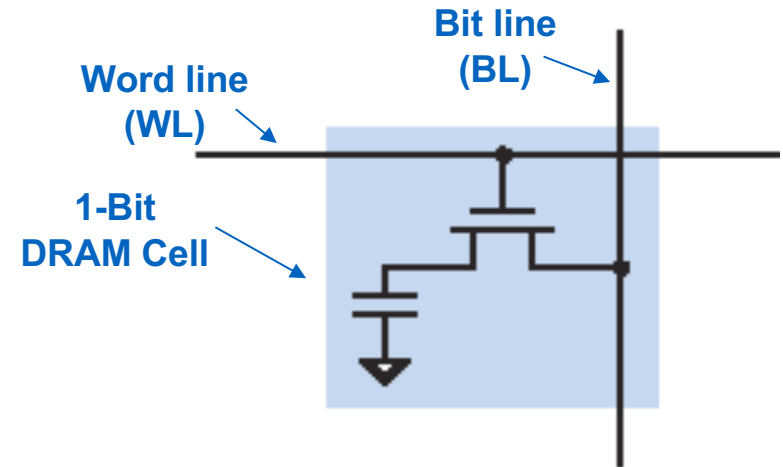
Common Organization of a DRAM Array*

- **Multiplexed address inputs to reduce pin count**
 - **Row & column addresses are sent sequentially through a shared subset of pins**
 - $\log_2 N$ bits each for an $N \times N$ bit cell array
 - Row address bits arrive first; followed by column address
 - **Row access**
 - Row-address strobe (RAS) loads row address bits into “row addr” latch to select 1 row
 - **Column access**
 - Column-address strobe (CAS) loads column address bits into “col addr” latch to select 1 column bit



DRAM Bit Cell

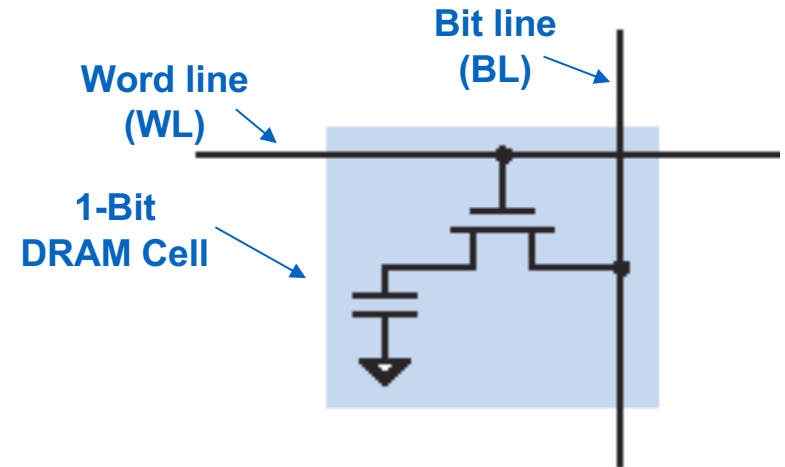
- Capacitor accessed through a transistor
- Capacitor is charged or discharged to produce a 1 or a 0
- DRAM cells lose their state over time and must be refreshed periodically, hence the name *dynamic*



1-Transistor 1-Capacitor (1T1C) DRAM Cell

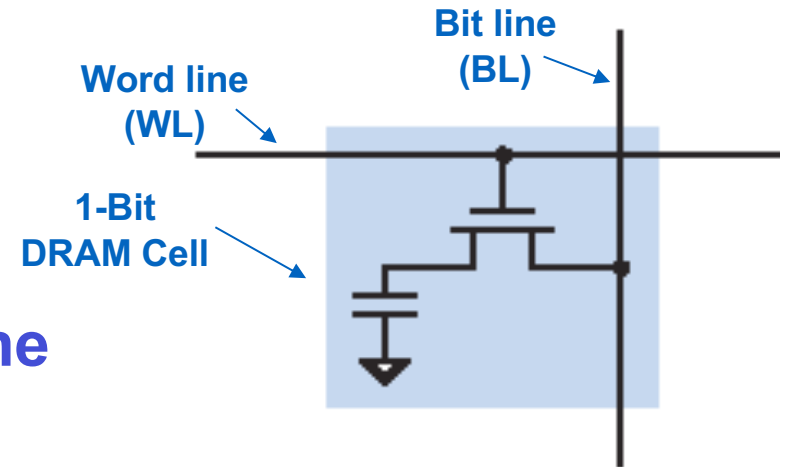
Write a DRAM Bit Cell

- Word line is asserted
- Bit line is driven with the desired value
 - Capacitor is charged by the bit line to store a 1
 - Or discharged by the bit line to store a 0



Read a DRAM Bit Cell

- Word line is asserted
- Bit line is *precharged* halfway between 0 and 1
- Capacitor voltage pulls the bit line slightly higher or lower
 - This also destroys the stored value (which the sense amplifier restores later)
- Sense amplifier detects this small change and amplifies it
 - If the bit line voltage increases, the sense amplifier drives it high (1); otherwise, it pulls it to ground (0).



Example: Read Access to a DRAM Array

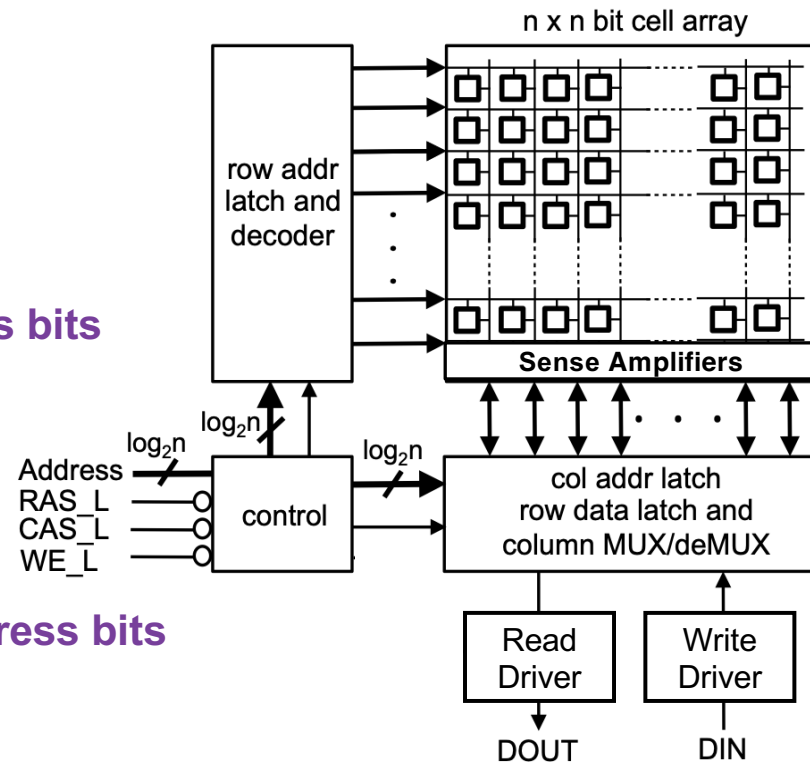
A DRAM bit cell array with 1024 rows x 1024 columns (1M bits)¹

① 10 row address bits arrive first;
RAS asserted

② 1024 bits are read out to row data latch

③ 10 column address bits arrive later;
CAS asserted

④ 1 bit returned through column MUX

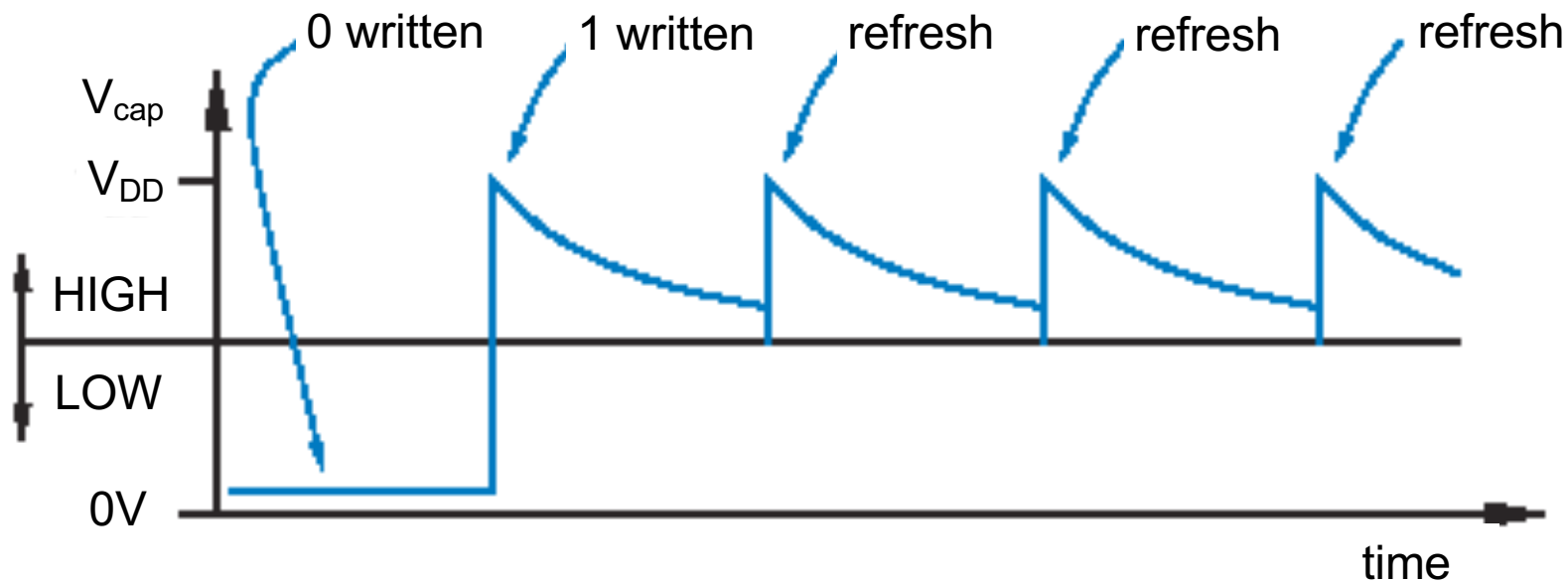


To retrieve a word, multiple DRAM arrays are read in parallel¹

¹ In a modern DRAM, a bit cell array typically has more rows than columns (e.g., 64K rows x 8K columns). The columns are organized into groups of memory cells (typically group size=8), and all cells in a group share the same address and are read or written simultaneously.

DRAM Refresh

- **Capacitors discharge over time**
 - Bit cells must be periodically refreshed (e.g., every 64ms, technology dependent)
- **Refresh cycles recharge each memory bit**
 - An entire row is refreshed at a time – each row periodically accessed using RAS (i.e., read access), which restores the charge



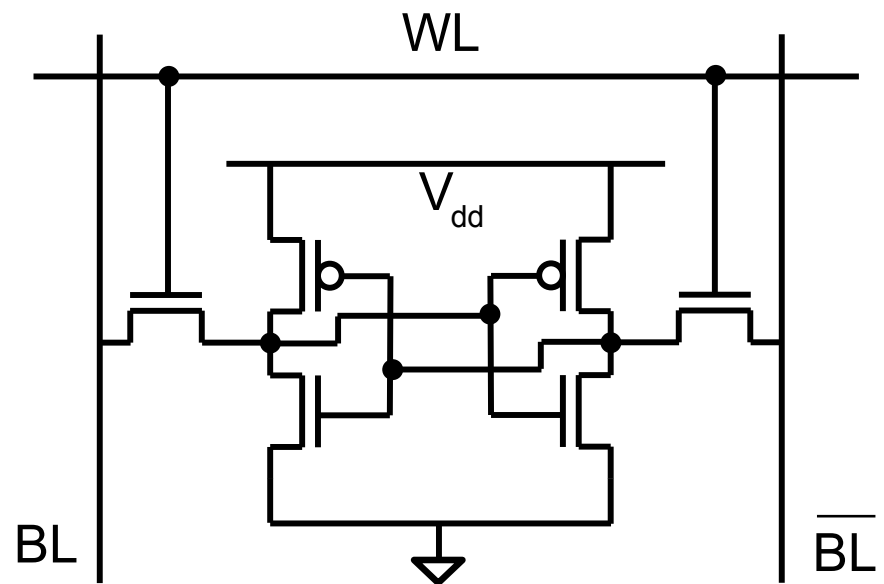
Static RAM (SRAM) Bit Cell

- **One cell requires six transistors**
 - The core is two cross-coupled inverters
- **Maintaining the state of the cell requires a constant power**
 - The cell is stable; no refresh cycles needed

6-Transistor (6T)
SRAM Cell

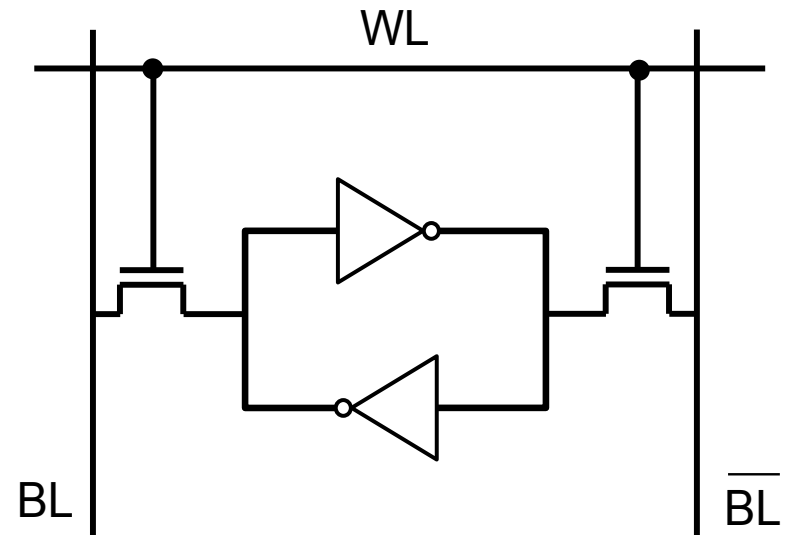
BL = bit line

WL = word line



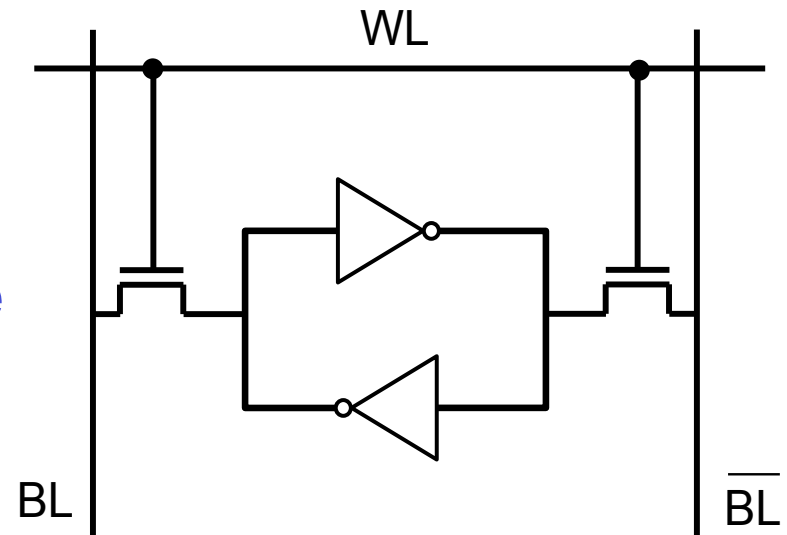
SRAM Write

- Drive one bit line high, the other low (depending on the desired value)
- Then turn on word line
- Bit lines over power cell with new value

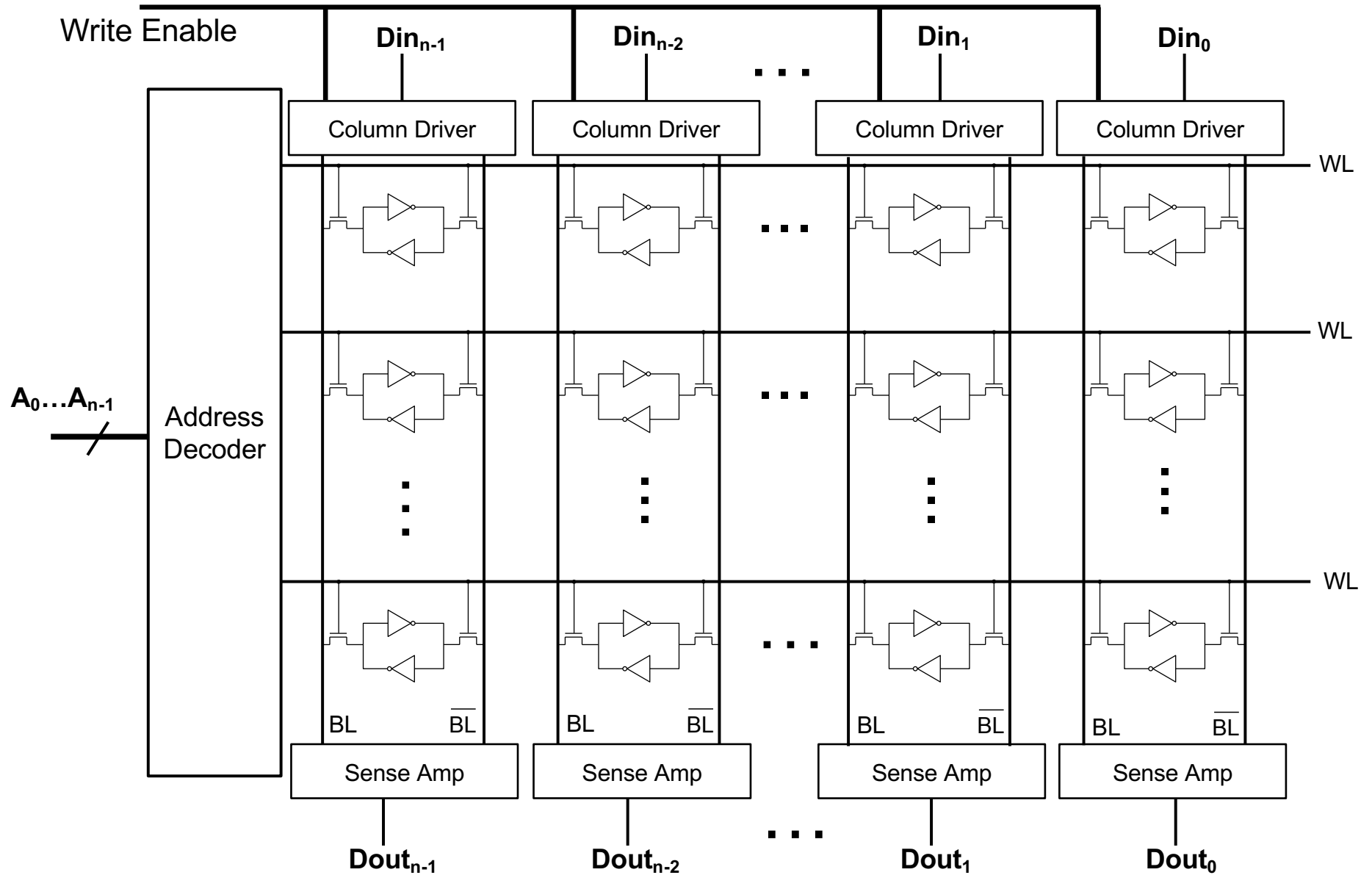


SRAM Read

- Precharge both bit lines high
- Then turn on word line
- One of the two bit lines will be pulled down by the cell
 - Change detected by sensor amplifier



SRAM Architecture*



*Optional reading: [Understanding SRAM](#) by SemiEngineering

Next Class

Single Cycle Microprocessor (H&H 7.1-7.3.4)